UNITED STATES PATENT AND TRADEMARK OFFICE **CERTIFICATE OF CORRECTION**

PATENT NO. : 6,780,707 B2 DATED

: August 24, 2004

INVENTOR(S) : Lee

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 7.

Line 5, "this-process" should read -- this process --.

Lines 14 and 18, "340' and" should read -- 340', and --.

Column 10,

Line 19, "layers EN, which" should read -- layers E_N, which --.

Line 31, "layers EN on" should read -- layers E_N on --.

Column 13,

Line 30, "layer; and (g) forming" should read -- layer; (g) forming --.

Line 31, "forming second" should read -- forming a second --.

Line 44, "wherein (e) comprises" should read -- wherein (h) comprises --.

Line 50, "wherein in (e) comprises" should read -- wherein (h) comprises --.

Line 51, "polishing the conductive material and the" should read -- polishing the first and second conductive type polysilicon layers and the --.

Column 14,

Line 19, "by farming a" should read -- by forming a --.

Line 26, "of claim wherein" should read -- of claim 8, wherein --.

Line 32, "the plugs" should read -- the metal plugs --.

Line 51, "opening, and" should read -- opening; and --.

Column 15,

Line 15, "opening the" should read -- opening, the --.

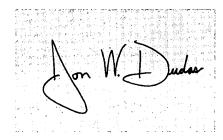
Line 22, "device inducting a" should read -- device including a --.

Line 43, "circuit axes, and" should read -- circuit area, and --.

Signed and Sealed this

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Thirty-first Day of May, 2005



JON W. DUDAS Director of the United States Patent and Trademark Office